
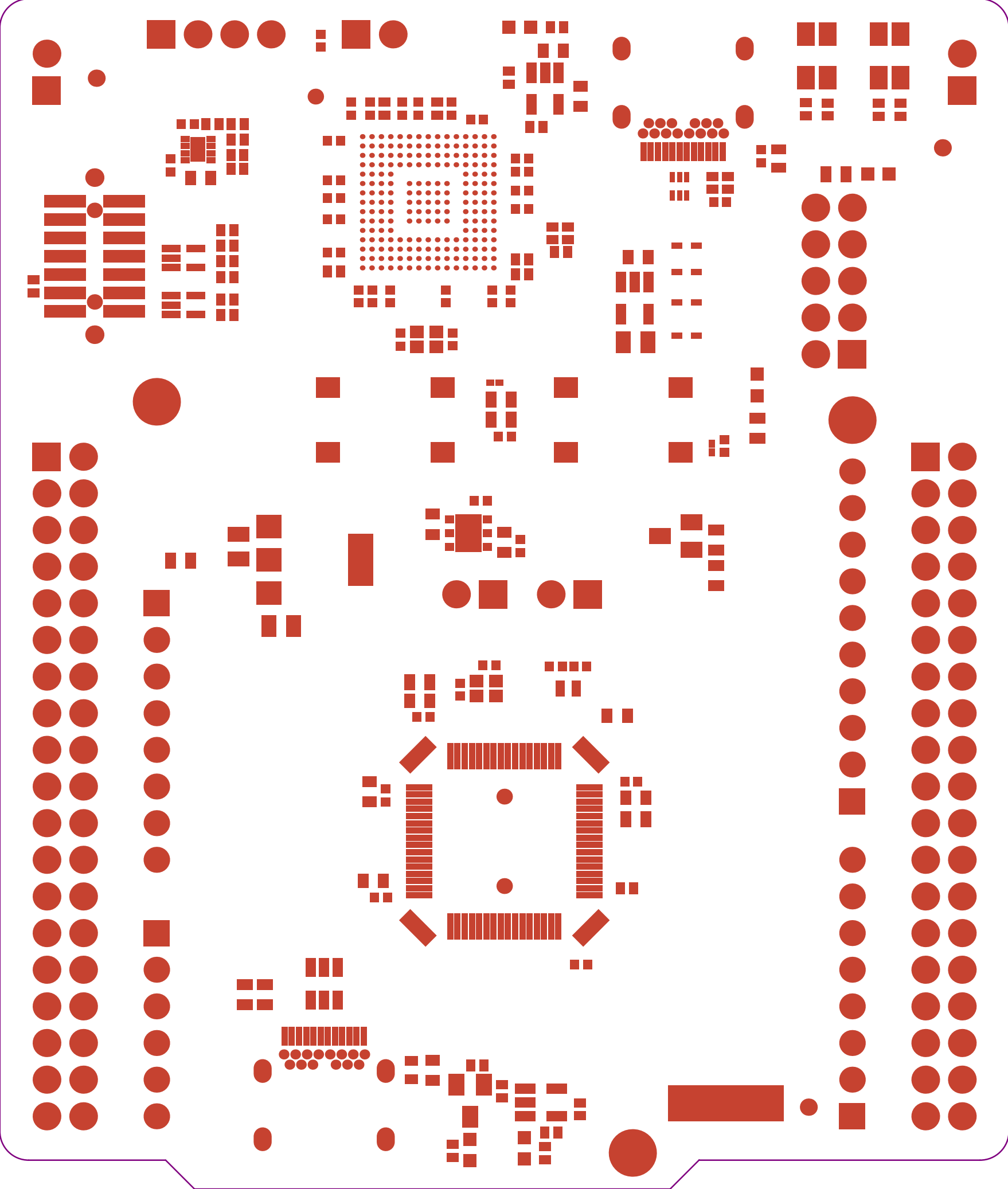

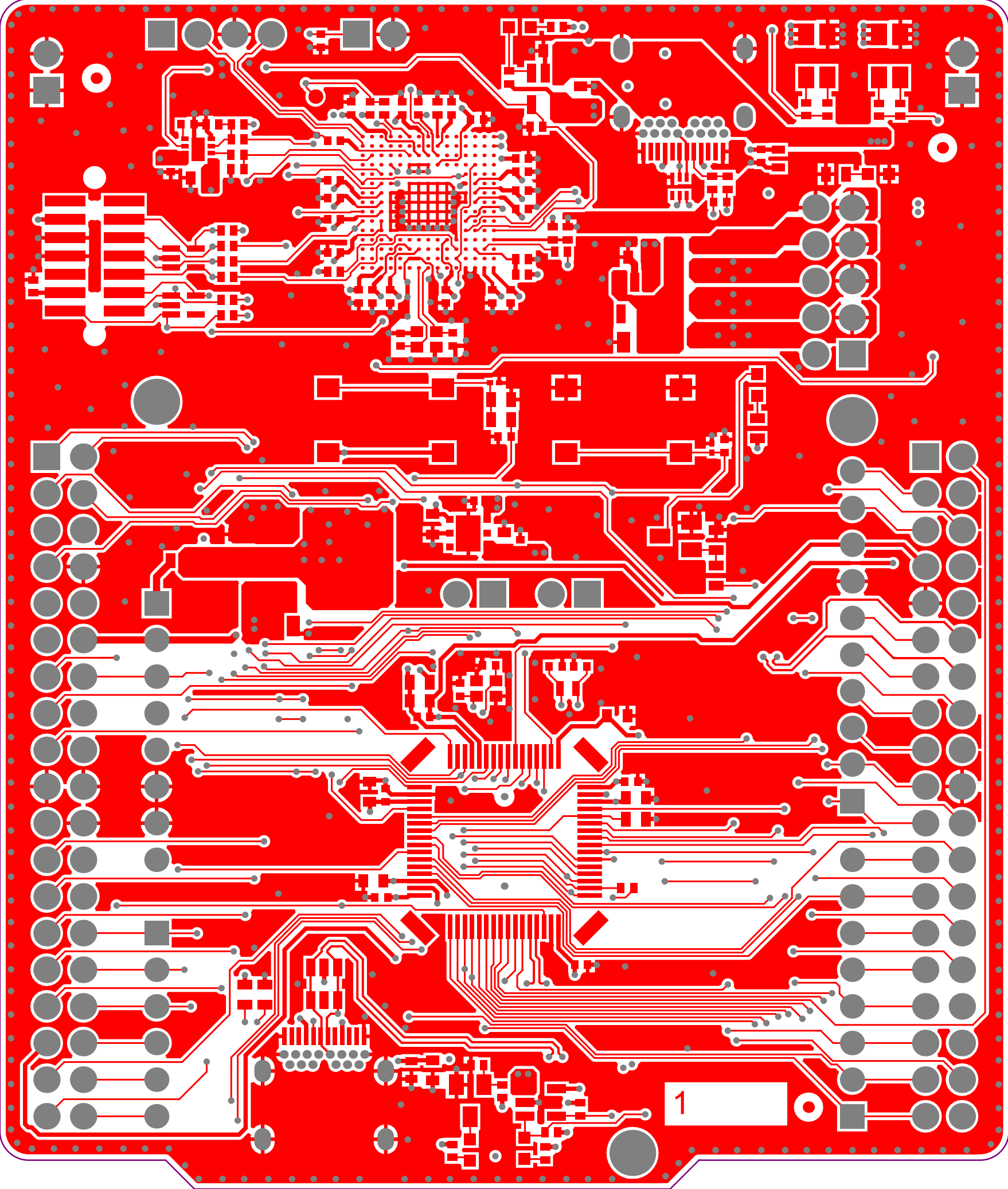



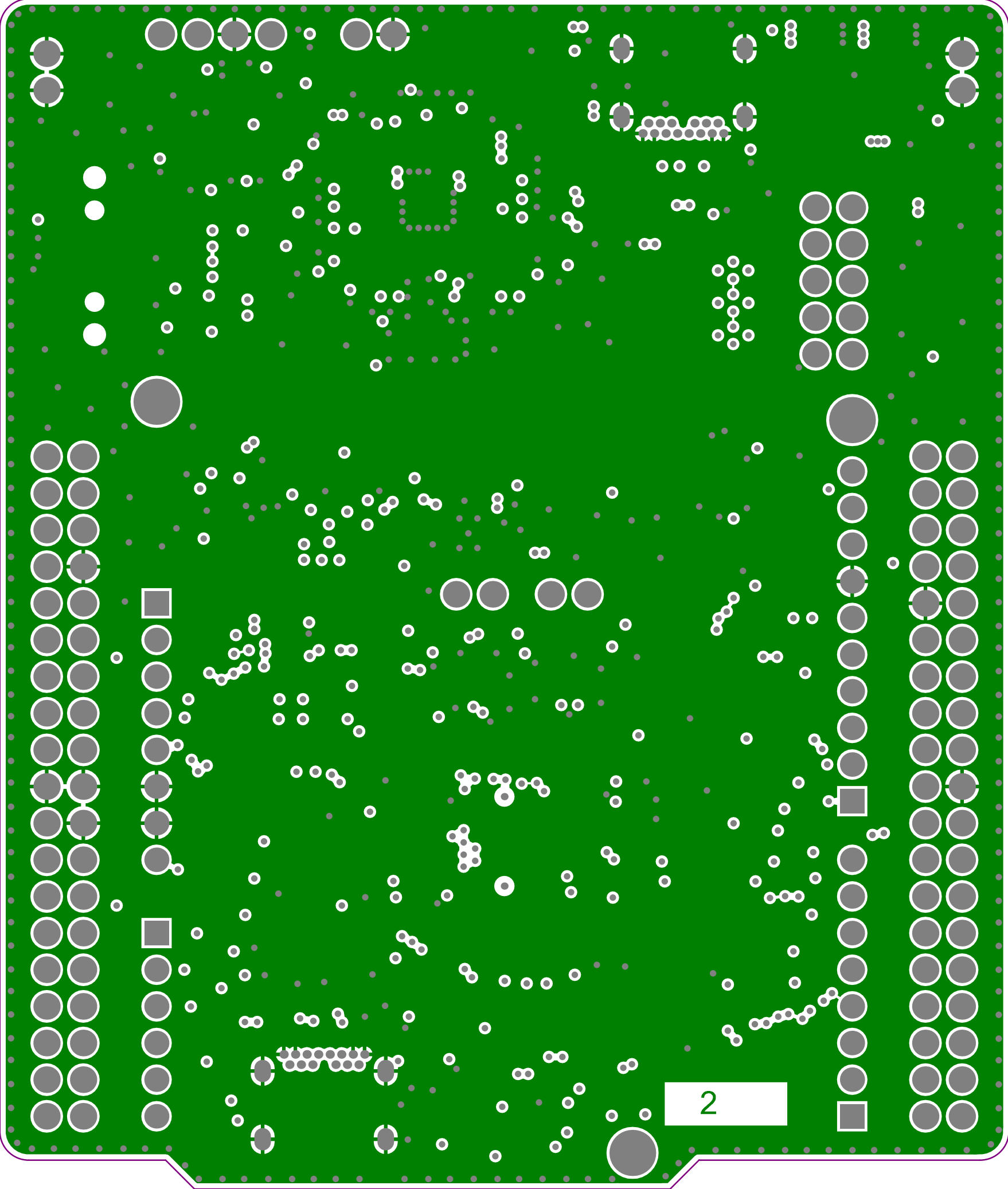
Project: NUCLEO64 H5 128K LEGACY		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	MB1814	
Date: 22-MAR-23	Rev: B	




Project: NUCLEO64 H5 128K LEGACY		
Layer: <b>Top Solder</b>	Gerber: <b>.GTS</b>	
Variant: [No Variations]	MB1814	
Date: 22-MAR-23	Rev: B	

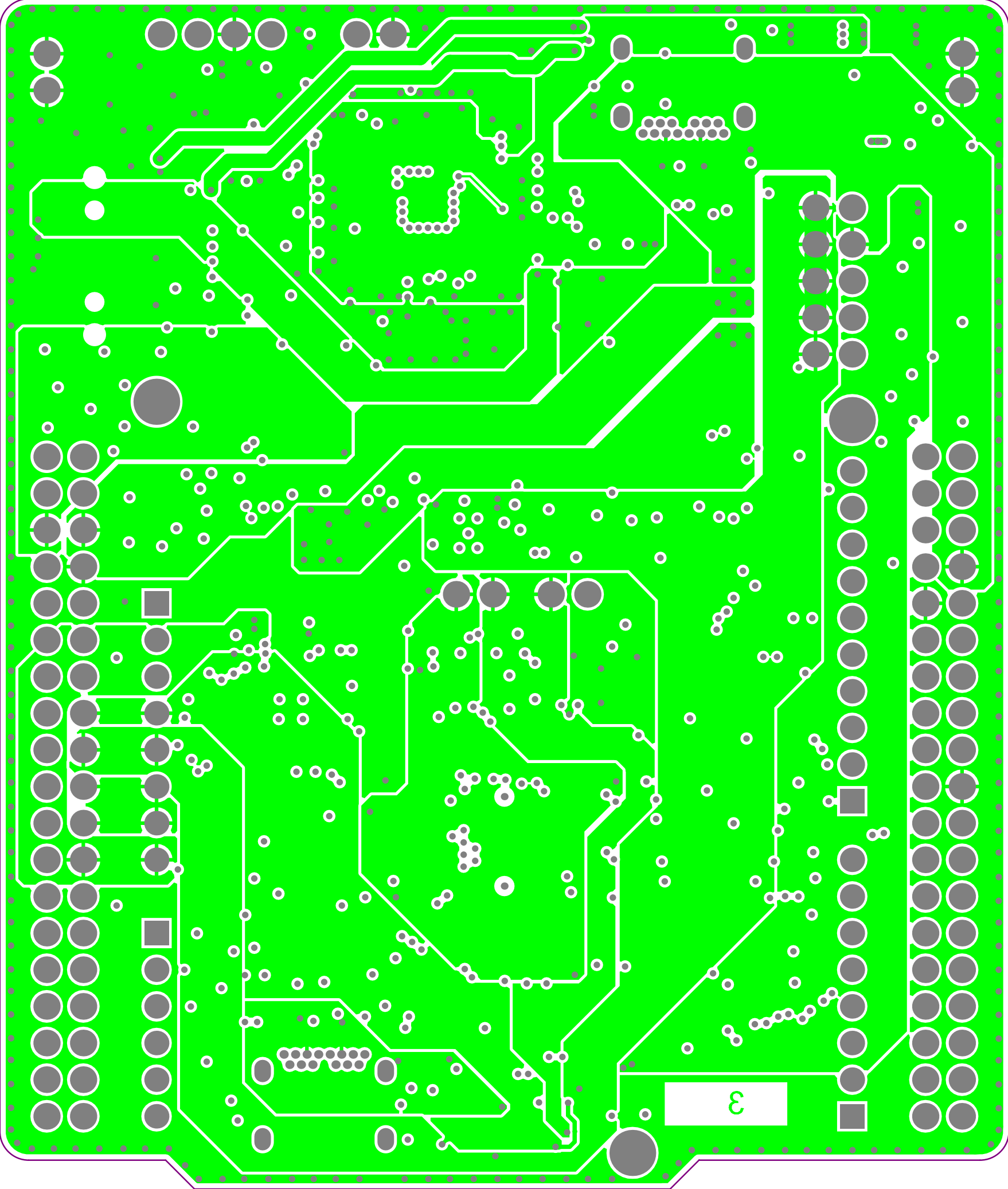



Project: NUCLEO64 H5 128K LEGACY		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: [No Variations]	MB1814	
Date: 22-MAR-23	Rev: B	

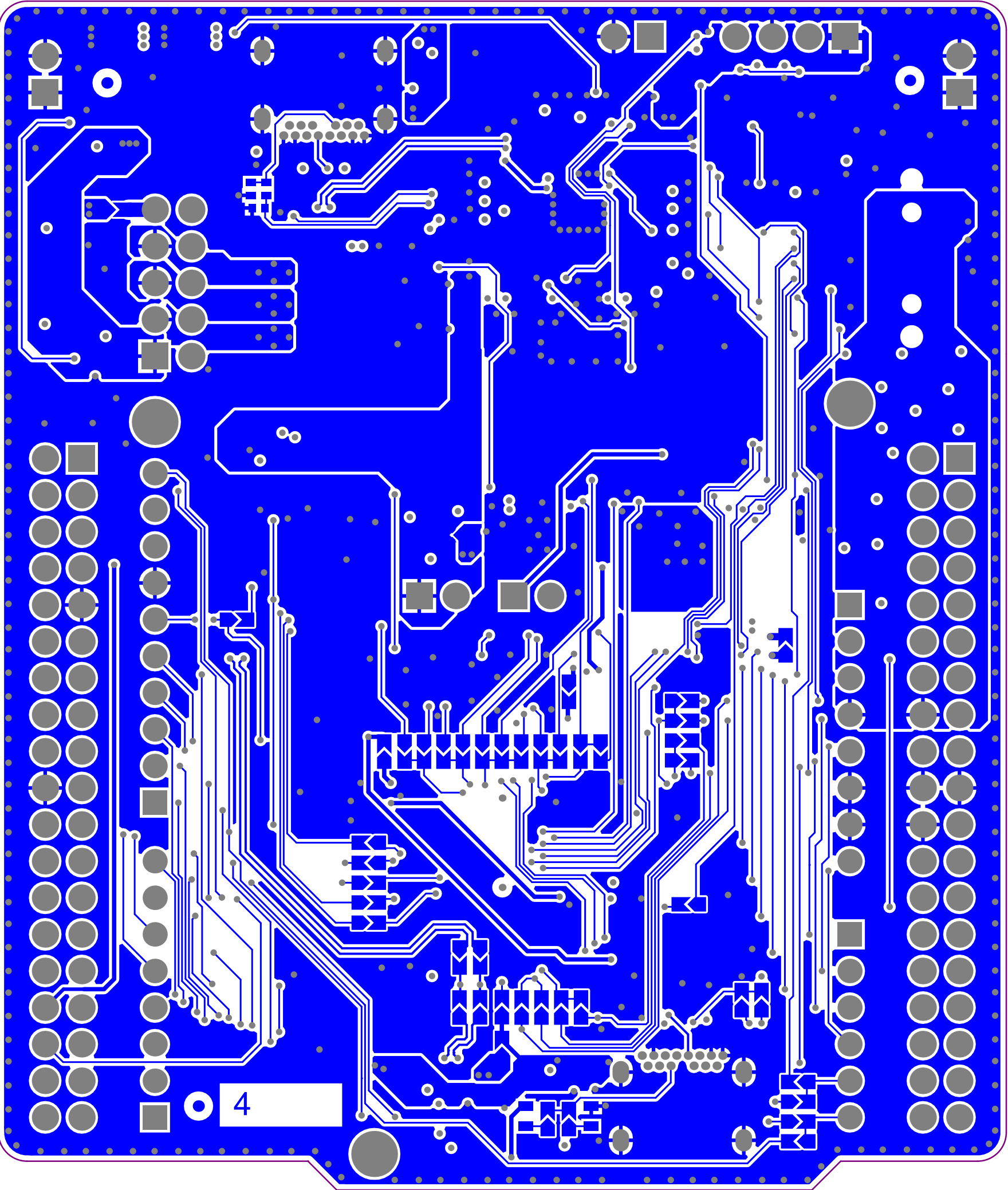


Project: NUCLEO64 H5 128K LEGACY		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	MB1814	
Date: 22-MAR-23	Rev: B	



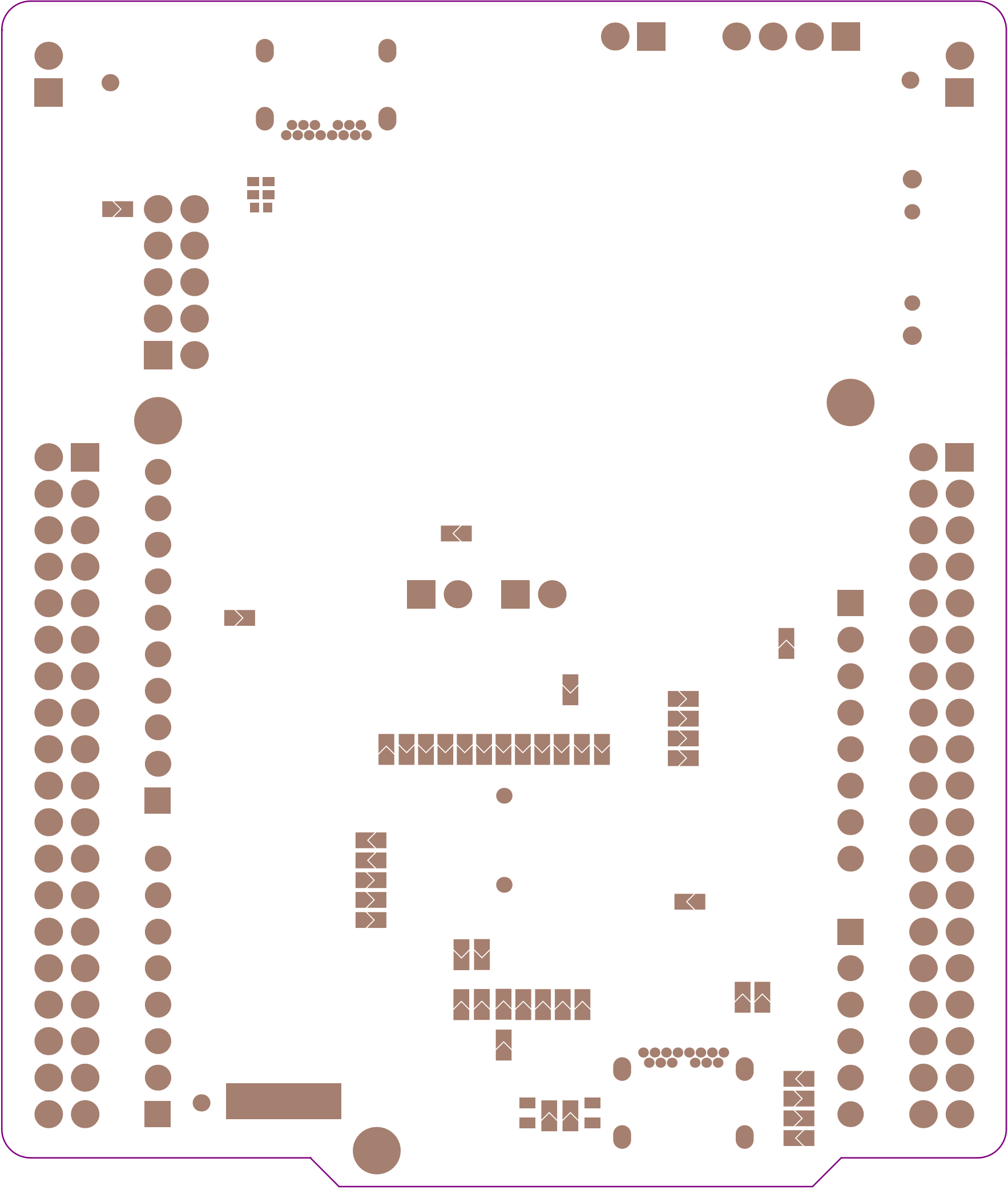



Project: NUCLEO64 H5 128K LEGACY		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	MB1814	
Date: 22-MAR-23	Rev: B	

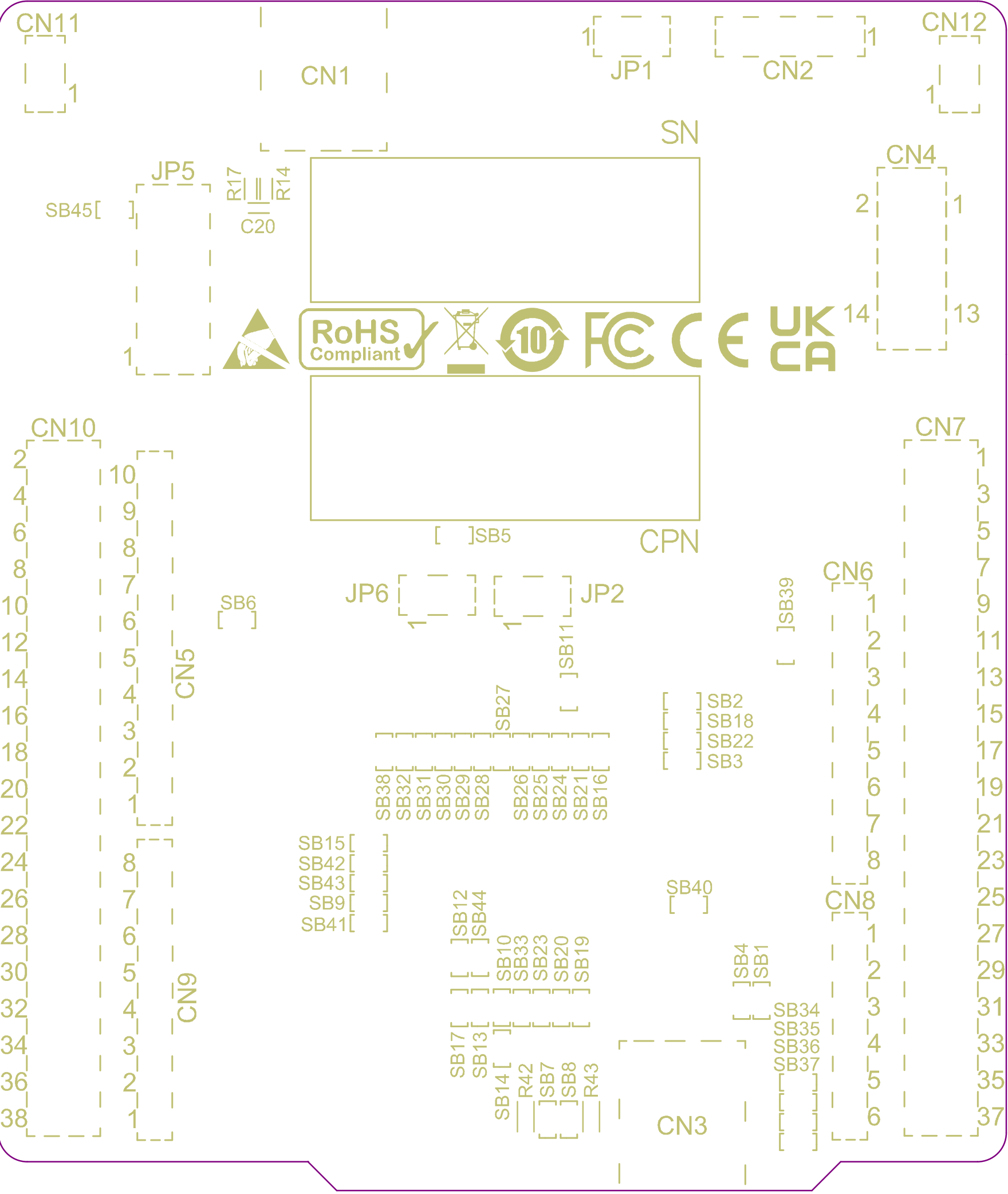



Project: NUCLEO64 H5 128K LEGACY	
Layer: Bottom Layer	Gerber:.GBL
Variant: [No Variations]	MB1814
Date: 22-MAR-23	Rev: B





Project: NUCLEO64 H5 128K LEGACY		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	MB1814	
Date: 22-MAR-23	Rev: B	



Project: NUCLEO64 H5 128K LEGACY		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	MB1814	
Date: 22-MAR-23	Rev: B	



« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

A. MATERIAL : FR-4 ☐ TG-170 ☒ TG-150 ☐ TG-140

B. MATERIAL FAMILY : N/A

C. SOLDERMASK COLOR : ☐ GREEN ☒ WHITE ☐ RED ☐ BLACK

D. SILKSCREEN COLOR : ☐ WHITE ☐ YELLOW ☐ BLACK ☒ Blue ink PANTONE 2955

E. SURFACE FINISH : ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN

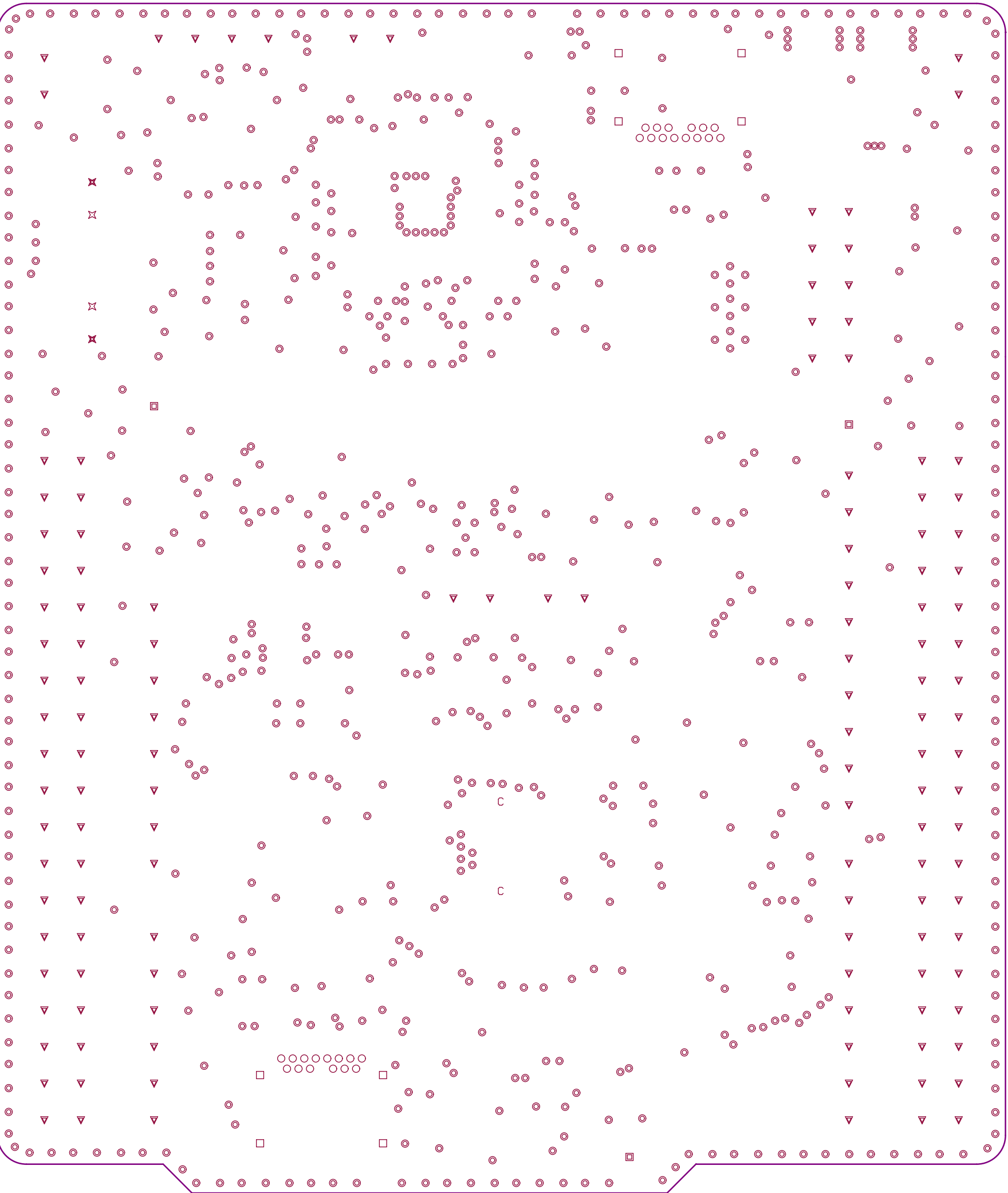
☐ HASL ☐ HASL (PB-FREE) ☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL : ☐ NO ☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA : PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.  
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP : SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

\*\*Plating type :  
lead Gold



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3,5	
1	Top Layer	Copper	0,042mm		
	Dielectric 1	PP-IT-180A	0,106mm	4,2	
2	Signal Layer 1	Copper	0,035mm		
	Dielectric 2	FR4	1,248mm	4,2	
3	Signal Layer 2	Copper	0,035mm		
	Dielectric 3	PP-IT-180A	0,106mm	4,2	
4	Bottom Layer	Copper	0,042mm		
	Bottom Solder	Solder Resist	0,015mm	3,5	
	Bottom Overlay				

PCB : TYPE 3

ASPECT-RATIO, AXE Z :  
6:1 to 8:1  
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT  
TRACKS : 0.120mm  
GAPS : 0.120mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
⊙	715	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
○	28	0,400mm (15,75mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
□	8	0,450mm (17,72mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	0,850mm (33,47mil)	0,400mm (15,75mil)
✕	2	0,970mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
C	2	1,000mm (39,37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
▽	132	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
✕	2	1,190mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
◻	3	3,200mm (125,98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
	892 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: NUCLEO64 H5 128K LEGACY

Layer: Drill Drawing

Variant: [No Variations]

Date: 22-MAR-23

Gerber: .DRL

MB1814

Rev: B

